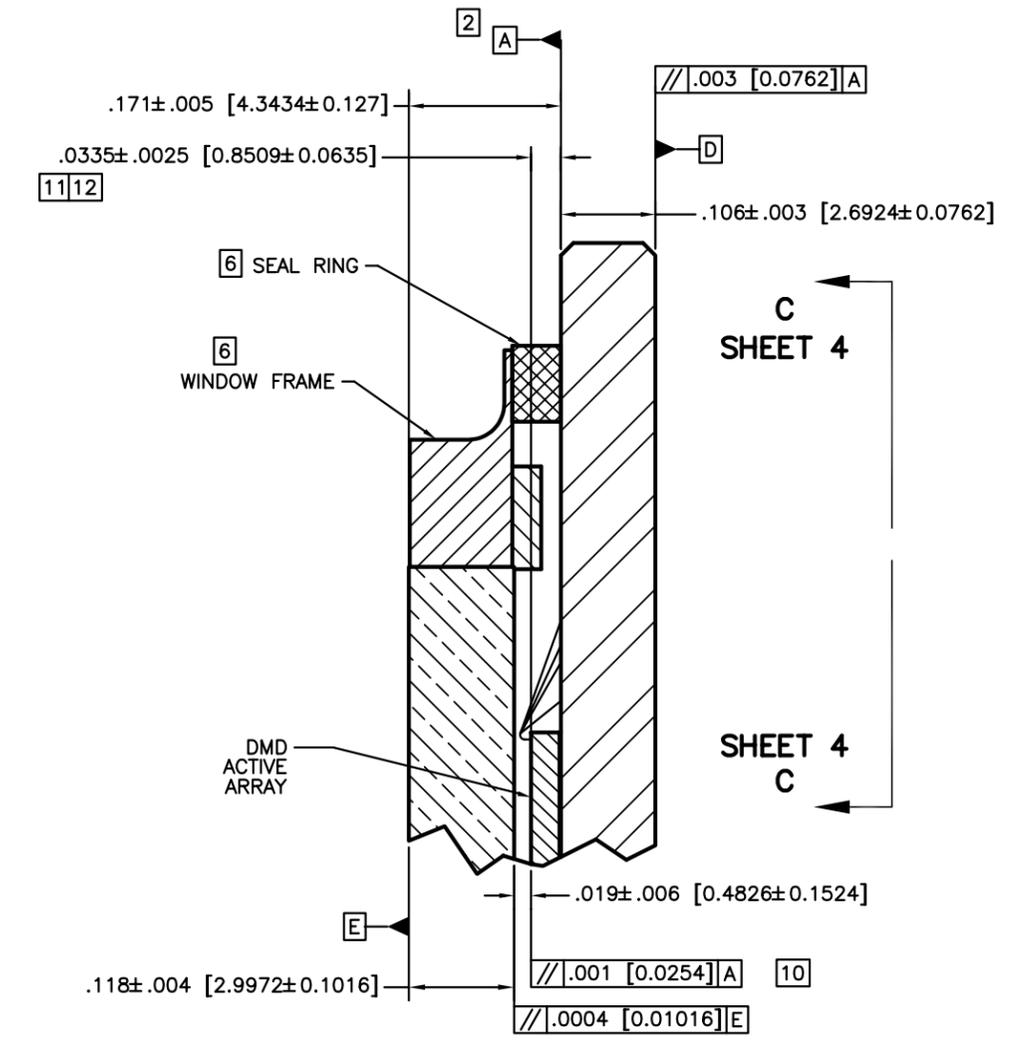


NOTES: UNLESS OTHERWISE SPECIFIED:

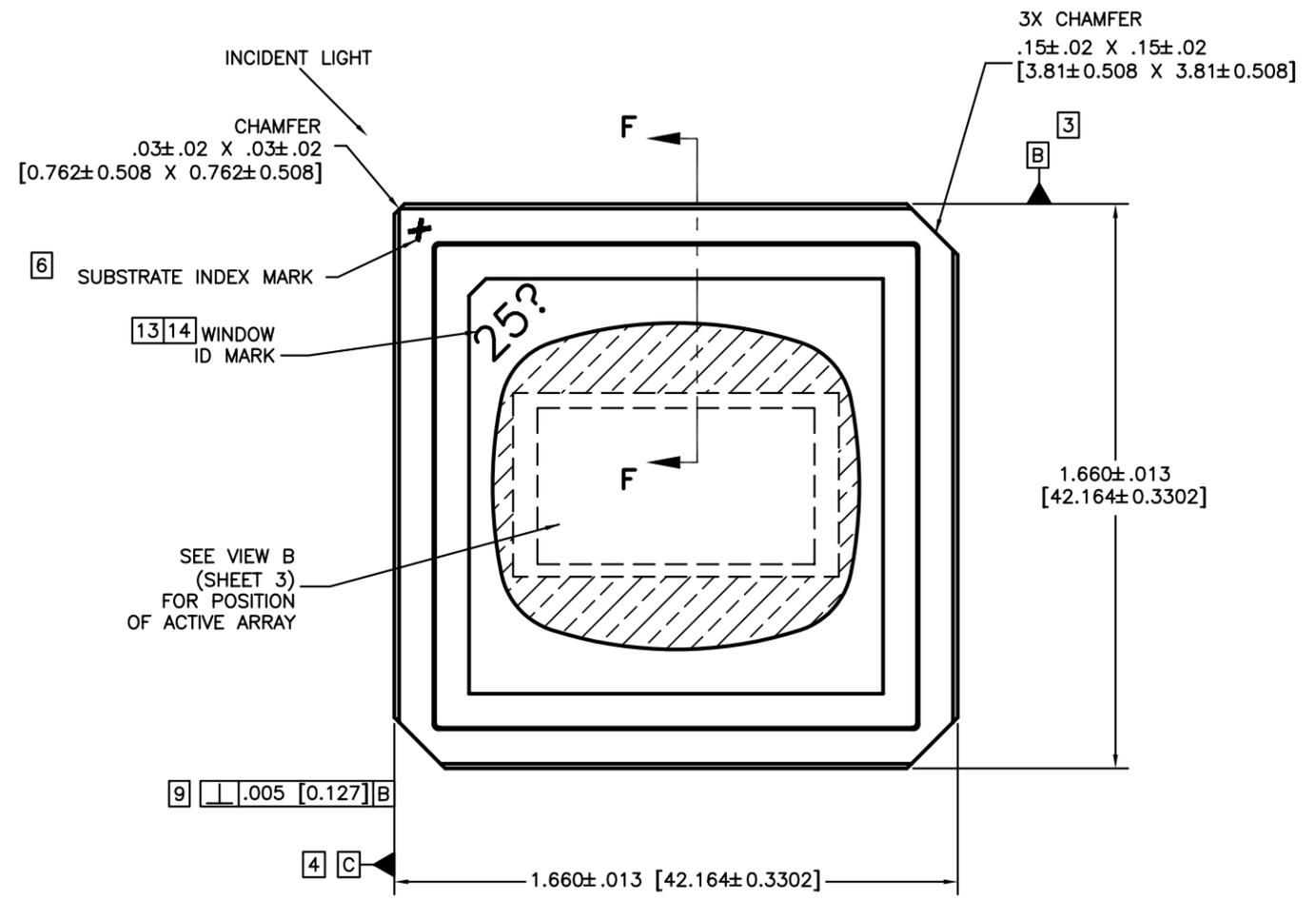
- 1 INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994.
- 2 DATUM A (SYSTEM INTERFACE PLANE) ESTABLISHED BY THREE DATUM AREAS SHOWN IN VIEW A (SHEET 2).
- 3 DATUM B ESTABLISHED BY TWO DATUM AREAS SHOWN IN VIEW A (SHEET 2).
- 4 DATUM C ESTABLISHED BY DATUM AREA SHOWN IN VIEW A (SHEET 2).
- 5 LOCALIZED BACKSIDE SURFACE FLATNESS APPLIES TO ENTIRE SURFACE.
- 6 SUBSTRATE INDEX MARK, BACK INDEX PAD, SYMBOLIZATION PAD, SEAL RING, AND WINDOW FRAME TO BE ELECTRICALLY CONNECTED TO VSS PLANE IN SUBSTRATE.
- 7 THE DIMENSIONS OF THE SYMBOLIZATION PAD REPRESENT THE APPROXIMATE SIZE AND LOCATION OF THE RECOMMENDED THERMAL INTERFACE AREA.
- 8 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND IS THE MAXIMUM VALUE ALLOWED.
- 9 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE.
- 10 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 11 DIE HEIGHT TOLERANCE APPLIES TO CENTER OF DMD ACTIVE ARRAY ONLY.
- 12 DMD ACTIVE ARRAY ROTATION AND LOCATION DIMENSIONS ARE RELATED TO DATUM A (PRIMARY), DATUM B (SECONDARY), AND DATUM C (TERTIARY).
- 13 WINDOW SHALL BE ORIENTED SUCH THAT I.D. MARK ALIGNS WITH SUBSTRATE INDEX MARK AS SHOWN.
- 14 ? IS A WILD CARD CHARACTER AND CAN BE ANY LETTER.

D  
C  
B  
A

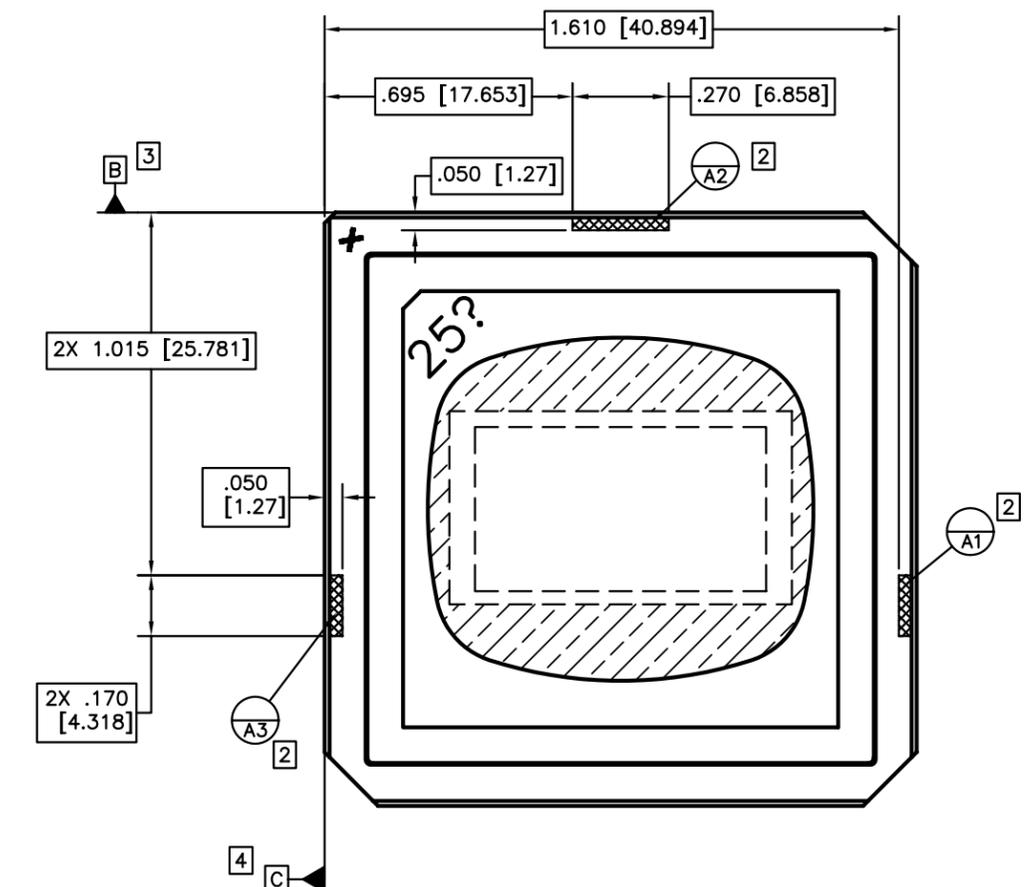
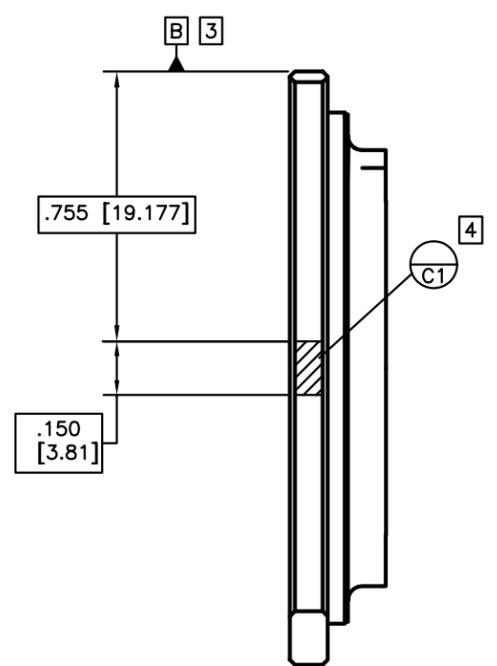
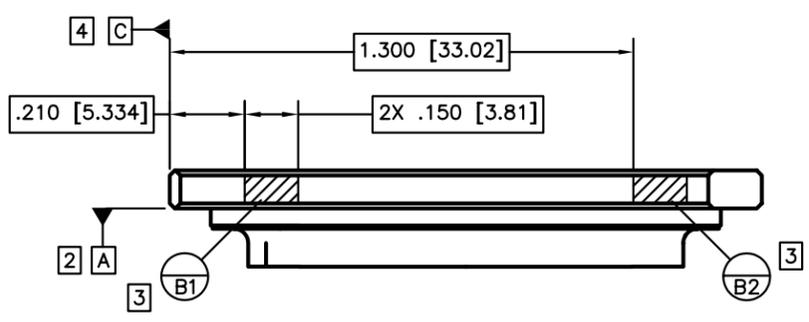
D  
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A



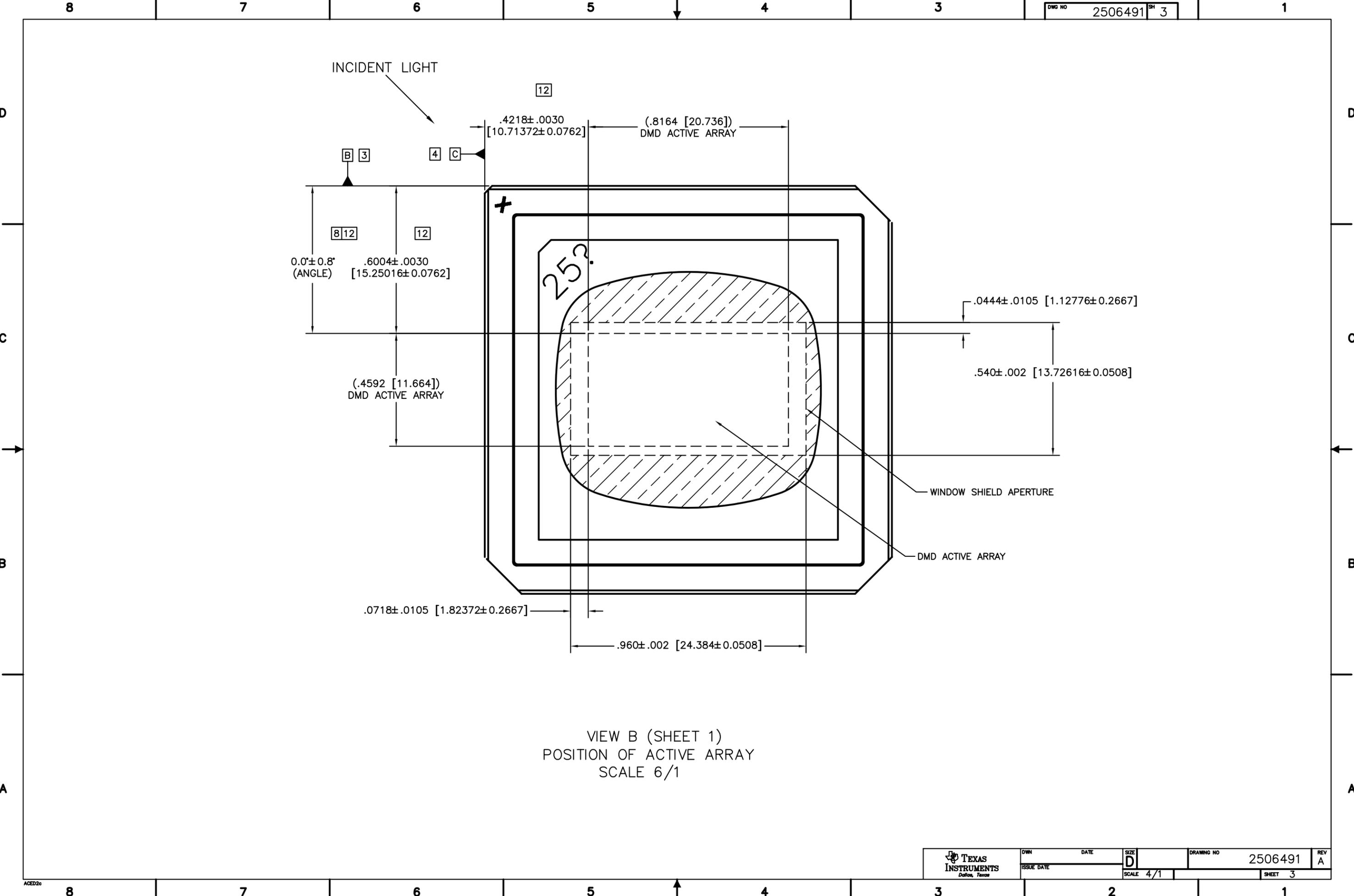
SECTION F-F  
SCALE 10/1



-1 QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES																														
			PARTS LIST																															
			UNLESS OTHERWISE SPECIFIED • DIMENSIONS ARE IN INCHES[MILLIMETERS] • TOLERANCES: ANGLES ± 1° 3 PLACE DECIMALS ±.005[0.127] 2 PLACE DECIMALS ±.01[0.254]	<table border="1"> <tr> <td>ENGR</td> <td>M. AVERY</td> <td>DATE</td> <td>2/28/05</td> </tr> <tr> <td>ENGR</td> <td>M. AVERY</td> <td>DATE</td> <td>2/28/05</td> </tr> <tr> <td>QA</td> <td></td> <td></td> <td></td> </tr> <tr> <td>APVD</td> <td></td> <td></td> <td></td> </tr> </table>	ENGR	M. AVERY	DATE	2/28/05	ENGR	M. AVERY	DATE	2/28/05	QA				APVD																	
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APVD																																		
			<ul style="list-style-type: none"> <li>REMOVE ALL BURRS AND SHARP EDGES</li> <li>CONCENTRICITY MACHINED DIAMETERS .010 FIM</li> <li>DIMENSIONAL LIMITS APPLY BEFORE PROCESSING</li> <li>PARENTHESES INFO FOR REF ONLY</li> </ul>	<table border="1"> <tr> <td colspan="2">HOLE TOLERANCE</td> </tr> <tr> <td>.013 THRU .125</td> <td>.126 THRU .251</td> </tr> <tr> <td>±.004 ±.001</td> <td>±.005 ±.001</td> </tr> <tr> <td>.501 THRU .750</td> <td>.751 THRU 1.000</td> </tr> <tr> <td>±.008 ±.001</td> <td>±.010 ±.001</td> </tr> <tr> <td></td> <td>1.001 THRU 2.000</td> </tr> <tr> <td></td> <td>±.012 ±.001</td> </tr> </table>	HOLE TOLERANCE		.013 THRU .125	.126 THRU .251	±.004 ±.001	±.005 ±.001	.501 THRU .750	.751 THRU 1.000	±.008 ±.001	±.010 ±.001		1.001 THRU 2.000		±.012 ±.001																
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VIEW A (SHEET 1 NOTES)  
DATUM A, B AND C DETAILS



VIEW B (SHEET 1)  
POSITION OF ACTIVE ARRAY  
SCALE 6/1



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